

# TEST REPORT Low Force Scalable Spring Finger

501-115070-17 2014.01.14

REV: A

#### 1. Purpose:

This is qualification test report. The purpose of this test is to evaluate the performance of Spring finger.

Testing was performed on below products to determine it compliance with the requirements of product specification 108-115061-1 Rev. A.

#### 2. Scope:

This is test report for Type C 3.6H connector. Testing was performed at TE Connectivity Shanghai Electrical Components Test Laboratory between Nov, 2013 and Jan, 2014.

#### 3. Conclusion:

The product met the electrical, mechanical, and environmental performance requirements of TE product specification 108-115061-1 REV A.

#### 4. Test samples:

Samples were taken randomly from current production. The following part numbers were used for test:

Description	Product Part No.
Type C 3.6h Spring Finger	3-2199250-4

#### 5. Test Requirements and Procedures Summary:

#### 5.1 Examination:

Test Description	Requirement	Procedures
Visual examination of product	Meets requirements of product drawing and applicable instructions on customer drawing, and application specification.	Visual, dimensional and functional per applicable inspection plan. In according with IEC 60512-1-1 Magnification 10x

#### 5.2 Electrical

Test Description	Requirement	Procedures
Low level contact resistance (LLCR)	25m $\Omega$ Max (Initial), 50m $\Omega$ Max (Final)	Subject mated connector to 20mV Max. open circuit at 100mA. Need to exclude wire resistance from measurement. (see 108-115061-1,Fig.2) Per EIA 364-23
Temperature rise	After tests maximum increase of contact temperature, 30°C max.	Measured at maximum rated current. Per EIA 364-70,Method 2



## 5.3 Environmental

Test Description	Requirement	Procedures				
Damp heat	No change to performance Contact resistance: Max. 50mOhm for Cu alloy Measure the resistance without opening the mating after test.	Temp 25-55 °C, RH 90-100% for 18 cycles of 24 hours each. The typical cycle in temp 25°C -> 55°C in 3 hours then maintain at 55°C for 9 hours Temp +55°C -> +25°C in 3 hours, maintain at 25°C for 9 hours. Recovery at 25°C. R/H 75% for 2 hours Mated tests: 10 mA (voltage is defined by current and resistance) IEC 60068-2-30 Db				
Vibration	No mechanical damage. No change to performance. Discontinuity <1us Max. 50mOhm	Frequency: 10 - 100 Hz: 3 m2/s3 100 - 500 Hz: -3dB/Oct. for: 3 x 60 min (X- Y- and Z-axis) in minimum deflection position. IEC60068-2-64Fh				
Shock	No mechanical damage. No change to performance. Discontinuity<1us Max. 50mOhm	Pulse shape half sine, peak acceleration 50 G, pulse 11 ms, 3 shocks in both directions in XYZ axis IEC60068-2-27Ea				
Nitric Acid Vapour test	Requirements: see Document ID: DTY11017- EN-2.0.	2 Hours 69±2 % concentration acid Acc. Document ID: DTY11017-EN- 2.0: Guideline for porosity testing of gold coated metallic connector springs – Nitric acid vapour test Blank cutting edges have to be sealed. IEC 600068-2-78				
Solderability	Soldering area shall have a minimum of 95% solder coverage.	245±3 $^{\circ}$ C, for 2-3 seconds,				
Resistance to reflow soldering heat	No cosmetic damage and shall meet requirement of subsequent test.	Test with reflow profile for soldering heat resistance described in Figure 1 through oven 3 times.				
thermal shock  No change to performance Contact resistance: Max. 50mOhm for Cu alloy Normal Force performance.		-40° /+85° C, transition time 5 minutes max, 25 cycles. Duration time: 30 minutes.  Recovery: 2 hours at 25° C, RH 75%.  In accordance with IEC 68-2-14-N.  (Nokia STR 1H2013, paragraph 3.3)				

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# 5.4 Mechanical

Test Description	Requirement	Procedures
Contact force at maximum working height (minimum deflection) low force scalable family	0.2N Min.	Compress spring to max. Working height to PWB surface. Force must be measured from return curve. Spring force-deflection curve described. Have to be fulfilled after 3 reflow cycles.
Contact force at minimum working height (maximum deflection) low force scalable family	1N + 20% Max.	Compress spring to max. Working height to PWB surface. Force must be measured from return curve. Spring force-deflection curve described. Have to be fulfilled after 3 reflow cycles.
Durability (Life cycle) Low Force Scalable Family	No functional damage Contact resistance : 50m Ω Max. Normal force should meet spec	1x max working range + 5000 x 50% working range Mate contact at max.20 matings per minute to 5000 cycles with rigid actuator shaft. Vertical direction deflection to a ½ of working height.
Durability (Spring dynamic test) Low Force Scalable Family	No functional damage Contact resistance : 50m Ω Max. Normal force should meet spec	1x max working range + 10000 x 50% working range Mate contact at max.20 matings per minute to 10000 cycles with rigid actuator shaft. Cycles for Maximum deflection case. Vertical direction deflection to a 1/2 of working height. Max. 20% loss of initial force. No technical function only to check the maximum lifetime.
Peeling Strength	3 N	Test method according STR retention force of contact. (see 108-115061-1, in Figure 4)
Push Strength	10 N Min.	Test method according STR peeling strength force of contact. (see 108-115061-1, in Figure 3)

# **5.5 Product Qualification Test Sequence**

Test group	а	b	С	d	е	f	g	h	i	j	k	m	n
Sample size	5	5	5	5	10	10	10	10	10	10	5	5	5
Visual examination of product	1,7	1,5	1,3	1,5	1,3	1,3	1,3	1,3	1,7	1,7	1,3	1,3	1,7
Low level contact resistance	2,6	2,4		2,4					2,6	2,6			2,6
Temperature rise			2										
Damp heat	4												
Vibration		3											
Shock				3									
Nitric Acid Vapour test					2								
Solderability						2							
Resistance to reflow soldering heat							2						
Contact force	3,5							2	3,5	3,5			3,5
Durability (Life cycle)									4				
Durability (Spring dynamic test)										4			
Peeling Strength											2		
Thermal Shock													4
Push Strength												2	

Numbers indicate sequence in which the tests are performed.

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## 6. Test Result

Group	Test Item	N	Conditi		Test Result		Require	Judgme
			on	Max	Min	Ave	ment No	nt
	Examination of Product	5	Initial	No physica	No physical damage occurred			Pass
	LLCR	5	Initial	11.55 mΩ	10.32 mΩ	11.08 mΩ	<25mΩ	Pass
	Contact Force	5	Initial	0.39 N	0.34 N	0.36 N	0.2N Min. at 3.3mm height	Pass
а	Common visc			1.10 N	1.06 N	1.08 N	1.2N Max. at 2.7mm height	Pass
u	Damp heat	5	Final	No physica	l damage occ	curred	No abnormal ities	Pass
	Contact Force	-	Initial	0.36 N	0.31 N	0.33 N	0.2N Min. at 3.3mm height	Pass
		5		1.08 N	1.03 N	1.16 N	1.2N Max. at 2.7mm height	Pass
	LLCR	5	Final	12.95 mΩ	11.35 mΩ	12.25 mΩ	<50mΩ	Pass
	Examination of Product	5	Final	No physical damage occurred			No abnormal ities	Pass
	Examination of Product	5	Initial	No physica	l damage occ	curred	No abnormal ities	Pass
	LLCR	5	Initial	11.82 mΩ	10.55 mΩ	11.17 mΩ	<25mΩ	Pass
b	Vibration	5	Final		nuities of 1 n uration occur		No abnormal ities	Pass
	LLCR	5	Final	12.33 mΩ	11.51 mΩ	11.92 mΩ	<50mΩ	Pass
	Examination of Product	5	Final	No phys	ical damage	occurred	No abnormal ities	Pass
	Examination of Product	5	Initial	No physica	I damage occ	curred	No abnormal ities	Pass
С	Temperature rise	5	Final	13.55°C	11.08°C	12.58°C	30°C max.	Pass
	Examination of Product	5	Final	No physica	No physical damage occurred			Pass
d	Examination of Product	5	Initial	No physica	l damage occ	curred	ities No abnormal ities	Pass
	LLCR	5	Initial	11.78 mΩ	10.65 mΩ	11.39 mΩ	<25mΩ	Pass
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1							No	
	Shock	5	Final	No physica	al damage occ	curred	abnormal ities	Pass
	LLCR	5	Final	12.03 mΩ	10.32 mΩ	11.90 mΩ	<50mΩ	Pass
	Examination of Product	5	Initial	No physica	ıl damage occ	curred	No abnormal ities	Pass
	Examination of Product	10	Initial	No physica	al damage occ	No abnormal ities	Pass	
е	Nitric Acid Vapor Test	10	Final	No physica	al damage occ	See Doc.1101 7- N-2.0.	Pass	
	Examination of Product	10	Final	No physica	ıl damage occ	No abnormal ities	Pass	
	Examination of Product	10	Initial	No physica	al damage occ	curred	No abnormal ities	Pass
f	Solderability	10	Final		area have a r r coverage.	minimum of	95% solder coverage	Pass
	Examination of Product	10	Final	No physica	ıl damage occ	No abnormal ities No	Pass	
	Examination of Product	10	Initial	No physica	No physical damage occurred			Pass
g	Resistance to reflow soldering heat	10	Final	No physica	al damage occ	No abnormal ities	Pass	
	Examination of Product	10	Final	No physica	al damage occ	curred	No abnormal ities	Pass
	Examination of Product	10	Initial	No physica	al damage occ	curred	No abnormal ities	Pass
h	Contact force	10	Initial	0.37N	0.32N	0.35N	0.2N min. at 3.3mm height	Pass
"	Contact force		iiiliai	1.10N	1.03N 1.06N		1.2N max. at 2.7mm height No	Pass
	Examination of Product	10	Final	No physica	No physical damage occurred			Pass
	Examination of Product	10	Initial	No physica	al damage occ	curred	No abnormal ities	Pass
	LLCR	10	Initial	11.35mΩ	10.76 mΩ	11.03 mΩ	<25mΩ	Pass
i	Contact force	10	Initial	0.38N	0.35N	0.36N	0.2N min. at 3.3mm height	Pass

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				1.08N	1.05N	1.06N	1.2N max. at 2.7mm height	Pass
	Durability(5000 life cycle)	10	Final	No physica	al damage oc	curred	No abnormal ities	Pass
	Contact force	10	Final	0.34N	0.31N	0.33N	0.2N min. at 3.3mm height	Pass
	Contact force		1 11101	1.08N	1.05N	1.06N	1.2N max. at 2.7mm height	Pass
	LLCR	10	Final	11.92mΩ	10.83 mΩ	11.75 mΩ	<50 mΩ	Pass
	Examination of Product	10	Final	No physica	al damage oc	curred	No abnormal ities	Pass
	Examination of Product	10	Initial	No physica	al damage oc	curred	No abnormal ities	Pass
	LLCR	10	Initial	11.60mΩ	10.49 mΩ	11.08 mΩ	<25mΩ	Pass
	Contact force	10	Initial	0.38 N	0.35 N	0.36 N	0.2N min. at 3.3mm height	Pass
				1.08 N	1.05 N	1.06 N	1.2N max. at 2.7mm height	Pass
j	Durability(spring dynamic test)	10	Final	No physica	al damage oc	No abnormal ities	Pass	
	Contact force	10	Final	0.35 N	0.32 N	0.33 N	0.2N min. at 3.3mm height	Pass
	Contact force			1.11 N	1.08 N	1.10 N	1.2N max. at 2.7mm height	Pass
	LLCR	10	Final	12.91mΩ	10.55 mΩ	11.76 mΩ	<50mΩ	Pass
	Examination of Product	10	Final	No physica	al damage oc	curred	No abnormal ities	Pass
	Examination of Product	5	Initial	No physica	al damage oc	curred	No abnormal ities	Pass
k	Peeling Strength	5	Initial	49.1 N	35.3 N	43.7 N	3N Min.	Pass
	Examination of Product	5	Final	No physical damage occurred			No abnormal ities	Pass
m	Examination of Product	5	Initial	. ,	al damage oc	1	No abnormal ities	Pass
'''	Push Strength	5	Initial	67.5 N	55.9 N	63.2 N	10N Min.	Pass
	Examination of Product	5	Final	No physica	al damage oc	curred	No abnormal	Pass

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	Examination of Product	5	Initial	No physica	l damage occ	No abnormal ities	Pass	
	LLCR	5	Initial	11.52 mΩ	10.08 mΩ	11.33 mΩ	$<25$ m $\Omega$	Pass
	Contact Force	5	Initial	0.38 N	0.36 N	0.37 N	0.2N min. at 3.3mm height	Pass
	Contact Force			1.10 N	1.06 N	1.08 N	1.2N max. at 2.7mm height	Pass
n	Thermal Shock	5	Final	No physica	l damage occ	No abnormal ities	Pass	
	Contact Force	5	Final	0.34 N	0.32 N	0.33 N	0.2N min. at 3.3mm height	Pass
				1.06 N	1.02 N	1.04 N	1.2N max. at 2.7mm height	Pass
	LLCR	5	Final	12.48 mΩ	12.48 mΩ   10.92 mΩ		<50 <b>m</b> Ω	Pass
	Examination of Product	5	Final	No physica	l damage occ	No abnormal	Pass	

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**END** 

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